

Channel Talk

FROM LAIRD PERFORMANCE MATERIALS

April 2020

SERVING YOU

With dedication by and excellent cooperation from you, our partners, Laird has successfully guided operations and our responsiveness during the global pandemic caused by the outbreak of the coronavirus. We appreciate the great teamwork: satisfying buyer demand; making extra effort to focus on worker safety and product quality; meeting shipping expectations. When you succeed, we do. Should you need help, feel free to call or write us. And be sure to explore the variety of new tools to help you grow your sales faster now and throughout 2020. Channel Talk is our bi-monthly outreach dedicated to your success!

OUR NEWEST OFFERING: DISCOVER MORE

New for automotive and consumer markets is a **Soft SMD** (Surface Mount Device) Contact designed to be solder reflow compatible and suitable for automatic processing. It is offered in three **series**: Metalized PI film over PU foam, rectangular shapes or hourglass shapes; metalized PI film over silicone foam, rectangular shapes generally, two different compression strengths and customized dimensions available; and an electrically conductive elastomer with metalized fabric designed for low height (miniature profile 0.6mm-1.5mm) or small width/length and ideal for further customized shapes using die-cutting. Review Laird's **Soft SMD Contact** capabilities.



ENDING THERMAL MATERIAL PUMP OUT

With larger dies and greater power in chip packages, design engineers face issues with effects of long-term cycling. Flexing action can lead to **thermal material pump-out** and possible edge failure. Read a new paper from Laird's Dr. Guoqiang Zhang on how to address **pump-out** and thus better protect CPUs, GPUs, MPUs and other components.



REVISED END-OF-LIFE POLICY

Manufacturers including Laird occasionally revise their product end-of-life **EOL policy** to better reflect market trends, potential obsolescence or other factors. Sometimes we elect to discontinue certain products which are at or nearing the end of their lifecycles. See a summary of our revised **EOL policy** including last purchase date and last shipping date. We encourage your questions.

RESOLVING MULTIPLE DESIGN ISSUES

Read and pass along Laird Performance Materials' recent **white paper** on mitigating EMI and heat issues using a single process design. Laird expert Eric Trantina says "EMI is only half of the problem. More component parts in these electronics make them more powerful, but also hotter. Design engineers face a quandary: how to effectively mitigate EMI and transfer heat in tight (and shrinking) spaces." Laird is a global leader in **multi-functional** solutions.



LOW DEFLECTION FORCE ABSORBER

Buyer response continues strong for **Softzorb MCS**, the soft, conformable absorber eliminating unwanted signal noise while also acting as a gap filler. Its low deflection force reduces stress on components or structures. Typically, an absorber is placed on the path of the emitted wave causing the unwanted noise. However, gaps can occur between radiating components in housings, thus producing coupling. Low deflection force enables Laird's **Softzorb MCS** to be placed in contact with components to fill cavities and eliminate coupling without shortening component life span. See our technical **datasheet** and **Softzorb MCS application notes**.



VIRUS RESPONSE: LAIRD CARES

Laird took key early steps at sites in China to ensure the health and safety of employees, channel partners and customers and slow the spread of the coronavirus. Laird's early actions were covered in an in-depth article in Industry Week magazine. [Read here](#) of our efforts. Similar measures are in place at Laird sites worldwide.

